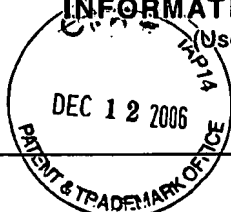


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PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)		APPLICANT Biehler, et al.	
Sheet 1 of 3		FILING DATE 12/8/2003	GROUP 1742



U.S. PATENT DOCUMENTS						
Ref. Desig.	Examiner's Initials	Document Number	Date	Name	Class/ Subclass	(If appropriate) Filing Date
1.		3,481,795*	12/1969	Lane		
2.		4,248,905*	12/1981	Harvey		
3.		4,358,884*	11/1982	Harvey et al.		
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8.		5,429,689*	7/1995	Shangguan et al.		
9.		5,527,628*	6/1996	Anderson et al.		

* Previously submitted in an IDS in parent application.

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1.		Anderson, et al., "Microstructural Modifications and Properties of Sn-Ag-Cu Solder Joints Induced By Alloying", Journal of Electronic Materials, vol. 31, no. 11, pp. 1166-1174 (2002)
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3.		Betrabet, H.S. et al., "Processing Dispersion-Strengthened Sn-Pb Solders To Achieve Microstructural Refinement And Stability," Script Metall. 25:2323-2328 (1991)*
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10.		Kuo, C.G. et al., "Fatigue Deformation Of In-Situ Composite Solders," 1st Int'l. Conf. Microstructures and Mechanical Properties of Aging Materials, ed. P.K. Liaw, R. Viswanathm, K.L. Murty, E.P. Simonen and D.R. Frear, The Minerals Metals & Materials Society, TMS, Warrendale, PA, pp. 417-423 (1993)*
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14.		Marshall, J.L. et al., "Composite Solders," IEEE Trans. Comp. Hybrids Manuf. Tech. 14(4):698-702 (1991)*
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